

(0,80mm) .0315"

HSEC8-DV SERIES

VERTICAL EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material:

Black Liquid Crystal Polymer
Contact: BeCu



Plating:

Au or Sn over 50µ" (1,27µm) Ni



Current Rating:

3.1A @ 30°C Temperature Rise (See website for details)

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15mm) .125" nominal

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

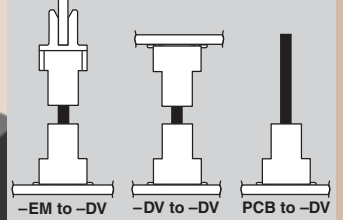
(0,10mm) .004" max (10-60)

Mates with:
1,6mm thick cards,
EEDP, HSC8, HSF8

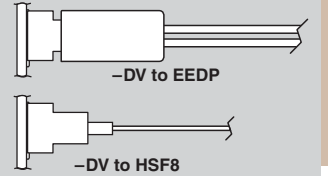


0,80mm HSEC8	Rated @ -3dB Insertion Loss
7,98mm Stack Height	
Single-Ended Signaling	8 GHz / 16 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps
For complete test data go to www.samtec.com?HSEC8 or contact sig@samtec.com	

BOARD-TO-BOARD APPLICATIONS

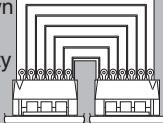


HIGH SPEED CABLE & FLEX APPLICATIONS



STANDARD & CUSTOM CARDS AVAILABLE

- Standard high speed interface cards for 19mm, 25mm & 30mm mated heights, single-ended & differential applications. See HSC8 Series.
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes



APPLICATION SPECIFIC OPTION



Note: Other Gold plating options available. Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

10, 13, 20, 25, 30, 37, 40, 49, 50, 60

-01 = (1,60mm) .062" thick card

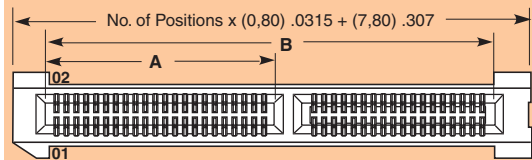
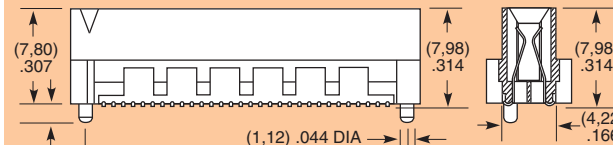
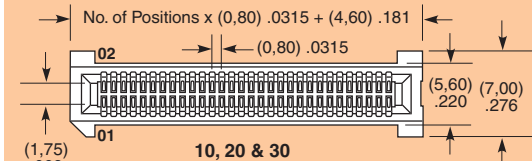
-S = 30µ" (0,76µm) Gold on contact, Matte Tin on tail

-K = (5,50mm) .217" DIA Polyimide Film Pick & Place Pad

-TR = Tape & Reel Packaging

-L = Latching Option (For use with EEDP.) (13, 25, 37, 49 only)

-BL = Board Locks (40, 50, 60 only) (Other sizes available. Contact Samtec)



CONNECTOR	CABLE*
HSEC8-113	EEDP-08
HSEC8-125	EEDP-16
HSEC8-137	EEDP-24
HSEC8-149	EEDP-32

POSITIONS PER ROW	A	B
13*	(6,10) .240	(15,00) .591
25*	(6,10) .240	(24,60) .969
37*	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

Positions where no dimensions are given do not have keying feature.
*Mates with EEDP Series.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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